General Description

The AOZ5277QI is a general-purpose Smart Power Stage (SPS) consisting of two asymmetrical MOSFETs and an integrated driver for high current, high frequency DC-DC converters.

The AOZ5277QI provides an output voltage signal (IMON), which represents the real-time module current with a gain of 5mV/A. The IMON signal can be directly used to replace inductor DCR sensing or resistor sensing in multiphase voltage regulator systems without the need for temperature compensation.

The AOZ5277QI also includes an accurate module temperature monitor (TMON). TMON is a voltage sourced signal with a gain of 8mV/°C.

The MOSFETs are individually optimized for operation in the synchronous buck configuration. The High-Side (HS) MOSFET is optimized to achieve low capacitance and gate charge for fast switching with low duty cycle operation. The Low-Side (LS) MOSFET has ultra-low ON resistance to minimize conduction loss. The standard 5mm x 6mm QFN package is optimally designed to minimize parasitic inductance for minimal EMI signature.

Features

- 3V to 20V power supply range
- 30V HS MOSFET provides better system ruggedness
- 60A continuous output current
  - Up to 100A for 10ms on pulse
  - Up to 150A for 10µs on pulse
- Optimized for switching frequency up to 1MHz
- Integrated current monitor (5mV/A) with 5% accuracy over temperature
- Integrated temperature monitor (8mV/°C) with 2% accuracy
- Fault Indicator
- Under-Voltage LockOut (UVLO) on VCC
- Under-Voltage LockOut (UVLO) on VIN
- High-Side MOSFET Over-Current and Short-Circuit Protection
- Zero Current Detect Function (ZCD)
- Over Temperature Protection (OTP)
- Standard QFN5x6-39L package

Applications

- Server systems
- High end CPU/GPU power stage
- Communications Infrastructure

Typical Application Circuit
**Ordering Information**

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Junction Temperature Range</th>
<th>Package</th>
<th>PreOVP</th>
<th>Environmental</th>
</tr>
</thead>
<tbody>
<tr>
<td>AOZ5277QI</td>
<td>-40°C to 125°C</td>
<td>QFN5x6-39L</td>
<td>Disabled</td>
<td>RoHS</td>
</tr>
<tr>
<td>AOZ5277QI-01</td>
<td>-40°C to 125°C</td>
<td>QFN5x6-39L</td>
<td>Active</td>
<td>RoHS</td>
</tr>
</tbody>
</table>

Contact local sales office for full product datasheet.

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**Pin Configuration**

![Pin Configuration Diagram](QFN5x6-39L_Top_View.png)
### Pin Description

<table>
<thead>
<tr>
<th>Pin Number</th>
<th>Pin Name</th>
<th>Pin Function</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>VOS</td>
<td>Output voltage sense.</td>
</tr>
<tr>
<td>2</td>
<td>AGND</td>
<td>Signal Ground.</td>
</tr>
<tr>
<td>3</td>
<td>VCC</td>
<td>5 V Bias for Internal Logic Blocks. Ensure to position a 1 µF MLCC directly between VCC and AGND (Pin 2).</td>
</tr>
<tr>
<td>4</td>
<td>PVCC</td>
<td>5 V Power Rail for High-Side and Low-Side MOSFET Drivers. Ensure to position a 1 µF MLCC directly between PVCC and AGND (Pin 5).</td>
</tr>
<tr>
<td>5, 40</td>
<td>PGND</td>
<td>Power Ground for High-Side and Low-Side MOSFET Gate Drivers. Ensure to connect 1 µF MLCC directly between PGND and PVCC (Pin 4).</td>
</tr>
<tr>
<td>6, 41</td>
<td>GL</td>
<td>Low-Side MOSFET Gate connection. This is for test purposes only.</td>
</tr>
<tr>
<td>7, 8, 9, 20, 21, 22, 23, 24</td>
<td>PGND</td>
<td>Power Ground pin for power stage (Source connection of Low-Side MOSFET).</td>
</tr>
<tr>
<td>10, 11, 12, 13, 14, 15, 16, 17, 18, 19</td>
<td>VSWH</td>
<td>Switching node connected to the Source of High-Side MOSFET and the Drain of Low-Side MOSFET.</td>
</tr>
<tr>
<td>25, 26, 27, 28, 29, 30</td>
<td>VIN</td>
<td>Power stage High Voltage Input (Drain connection of High-Side MOSFET).</td>
</tr>
<tr>
<td>31, 32</td>
<td>PHASE</td>
<td>This pin is dedicated for bootstrap capacitor AC return path connection from BOOT (Pin 33).</td>
</tr>
<tr>
<td>33</td>
<td>BOOT</td>
<td>High-Side MOSFET Gate Driver supply rail. Connect a 100 nF ceramic capacitor between BOOT and the PHASE (Pin 31 and 32).</td>
</tr>
<tr>
<td>34</td>
<td>PWM</td>
<td>PWM input signal from Controller IC. This input is compatible with 3.3 V and 5 V Tri-State logic levels.</td>
</tr>
<tr>
<td>35</td>
<td>EN</td>
<td>Output enable pin. When this pin is pulled to a logic low level, the IC disables most blocks. EN=HIGH enables all blocks inside IC and requires 4 µs power up time.</td>
</tr>
<tr>
<td>36</td>
<td>TMON/FLT</td>
<td>Temperature Monitor and Fault Flag Pin. TMON/FLT will be pulled HI (~ 3.3 V) or LOW (0 V) to indicate a fault condition (see Table 5). For multi-phase application, the TMON/FLT pin can be connected together as a common bus. The highest voltage representing the highest temperature among all phases will be sent to the PWM controller. No more than 470 pF total capacitance can be directly connected across TMON/FLT and AGND (Pin 2). A higher capacitance load is allowed with a series resistor (~ 1 kΩ) for up to 1 nF. At 0 °C and in normal operation, the output voltage is 0.6 V with a temperature coefficient value of 8 mV/°C. There is an internal pull up source to 3.3 V when a fault condition occurs.</td>
</tr>
<tr>
<td>37</td>
<td>OCSET/ZCD</td>
<td>Setting control for OCP limit threshold and Zero Cross Detect function (ZCD). OCP limit threshold is detected and latched 120 µs after device enabled. Refer to Table 3 for the resistor value for each current limit threshold level. After 120 µs, the OCP limit is set and this pin becomes ZCD control only. ZCD is active when this pin is floating or pulled HI.</td>
</tr>
<tr>
<td>38</td>
<td>IMON</td>
<td>Current Monitor output signal referenced to REFIN (Pin 39). Connect the IMON output to the appropriate Current Sense input of the controller. No more than 47 pF capacitance can be directly connected across IMON and REFIN pins. With a 100 Ω series resistor, up to 470 pF may be used.</td>
</tr>
<tr>
<td>39</td>
<td>REFIN</td>
<td>Input for external reference voltage for IMON (Pin 38). This voltage should be between 0.7 V and 2.0 V. Nominal value is 1.2 V. Place a low ESR ceramic capacitor (~ 0.1 µF) from this pin to AGND (Pin 2). Connect REFIN to the appropriate Current Sense Reference output from the controller.</td>
</tr>
</tbody>
</table>
Package Dimensions, QFN5x6-39L

**NOTE**
1. **CONTROLLING DIMENSION IS MILLIMETER.**
2. **CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.**
Tape and Reel Dimensions, QFN5x6-39L

### QFN5x6 39L_EP3 S Carrier Tape

![Diagram of QFN5x6 39L_EP3 S Carrier Tape]

#### UNIT: MM

<table>
<thead>
<tr>
<th>PACKAGE</th>
<th>A0</th>
<th>B0</th>
<th>K0</th>
<th>D0</th>
<th>DL</th>
<th>W</th>
<th>E</th>
<th>F</th>
<th>P0</th>
<th>P1</th>
<th>P2</th>
<th>T</th>
</tr>
</thead>
<tbody>
<tr>
<td>QFN5x6</td>
<td>5.30</td>
<td>±0.10</td>
<td>6.30</td>
<td>±0.10</td>
<td>1.15</td>
<td>±1.50</td>
<td>1.50</td>
<td>±0.10</td>
<td>12.00</td>
<td>±0.05</td>
<td>1.75</td>
<td>±0.05</td>
</tr>
</tbody>
</table>

### QFN5x6 39L_EP3 S Reel

![Diagram of QFN5x6 39L_EP3 S Reel]

#### UNIT: MM

<table>
<thead>
<tr>
<th>TAPE SIZE</th>
<th>REEL SIZE</th>
<th>M</th>
<th>N</th>
<th>W</th>
<th>W1</th>
<th>H</th>
<th>K</th>
<th>S</th>
<th>G</th>
<th>R</th>
<th>V</th>
</tr>
</thead>
<tbody>
<tr>
<td>12 mm</td>
<td>Ø330</td>
<td>Ø330</td>
<td>±0.50</td>
<td>13.0</td>
<td>±0.30</td>
<td>17.40</td>
<td>±1.00</td>
<td>ø330</td>
<td>±0.50</td>
<td>10.6</td>
<td>2.00</td>
</tr>
</tbody>
</table>

### QFN5x6 39L_EP3 S Tape

**Leader / Trailer & Orientation**

- **Unit Per Reel:** 3000pcs
  - Trailer Tape: 300 mm MIN. OR
  - Components Tape Orientation in Pocket
  - Leader Tape: 500 mm MIN. OR
### Part Marking

![Part Marking Diagram]

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Code</th>
<th>Year Code &amp; Week Code</th>
<th>Assembly Lot Code</th>
<th>Option Code</th>
<th>Special Code</th>
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</thead>
<tbody>
<tr>
<td>AOZ5277QI</td>
<td>AK00</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>AOZ5277Qi-01</td>
<td>AK01</td>
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</tr>
</tbody>
</table>

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